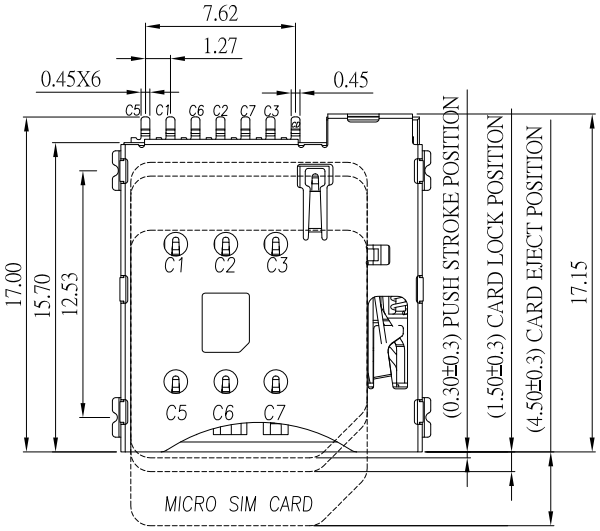
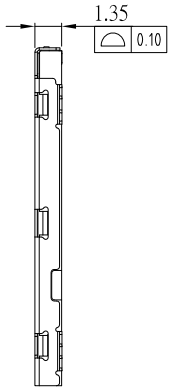
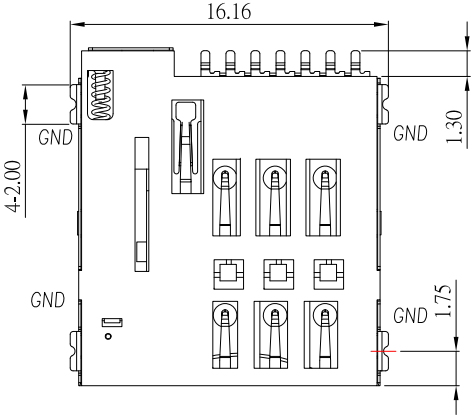
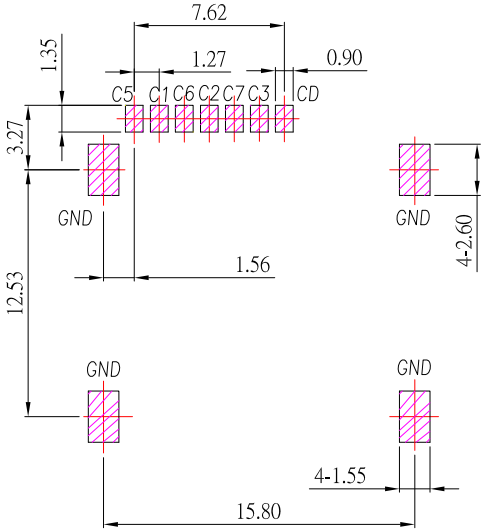
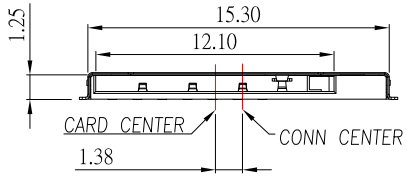


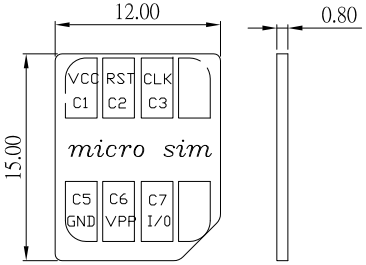






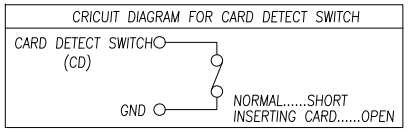
PCB LAYOUT





MICRO SIM CARD

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



Material:

1.Housing: LCP

2.Contact: Copper Alloy

3.Shell: Stainless Steel

Finish:

1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall

2.Shell: Nickel under Plated surface layer

ITEM NO.	DESCRIPTION	DRAWN	DATE

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2; Above 5 ~ 15 ±0.3; Above 15 ~ 30 ±0.4; Above 30 ~ 50 ±0.5; Angle ±0.3°

3RD. ANGEL'S | UNITS MM

DRAWN BY: Jack Lu	DATE 09/28/18	MAT'L	
CHECKED BY: Jacky Chen	DATE 09/28/18	FINISH	
APPROVED BY: Tony Kao	DATE 09/28/18	SCALE 1 : 1	SHEET NO. 1 of 1

TITLE	CONNECTOR		
MODLE	MICRO SIM PUSH. 7PIN H1.35		
DWG NO.	MSIM-135A-01BR-S304	SIZE	A4
PART NO.	MSIM-135A-01BR-S304	VER	R